The productronica celebrates 50 years and LPKF celebrates with it: Laser technology for the entire value chain of the electronics industry

- **New depaneling systems: CuttingMaster 2246 celebrates world premiere**
- **PCB prototyping: ProtoLaser turns 25**
- **Advanced Packaging: LIDE® ready for series production**

Munich/ Garbsen, October 10, 2025 – LPKF Laser & Electronics invites visitors to productronica 2025 in Munich from November 18 to 21. At **booth 305 in hall B2**, the company will present its portfolio of modern laser technologies for the electronics industry live – from prototyping systems and high-performance depaneling to laser plastic welding for electronic housings and thin glass processing for advanced packaging.

With new technologies, proven processes, and further developed solutions, LPKF once again offers all visitors a comprehensive insight into the diverse application possibilities of laser technology in electronics manufacturing.

"We have been represented at productronica since the early years of our almost 50-year company history. The trade fair offers us the ideal platform to present our innovative laser technologies along the entire electronics value chain to a broad audience," explains Dr. Klaus Fiedler, CEO of LPKF and also advisory board member of productronica.

World premiere: Depaneling systems with Tensor technology

Two new laser depaneling systems for industrial manufacturing take center stage:

- CuttingMaster 2246: Seen live for the first time, the system sets new performance standards with integrated Tensor technology. It supports SMEMA, HERMES, and OPC UA protocols and is prepared for Industry 4.0 environments.
- CuttingMaster 2240 Cx: A fully automated system for cost-effective mass production of rigid printed circuit boards, shown for the first time in the production line of Fraunhofer IZM. The integrated clamping and unloading unit eliminates the need for circulating work carriers.

25 years of ProtoLaser

Another highlight: the 25th anniversary of the ProtoLaser family. Since 2000, it has enabled laser structuring of printed circuit boards combined with mechanical processing, ideal also for thick PCBs and multilayers. Today, the ProtoLaser family processes feature widths down to 15 µm and a broad spectrum of materials – from FR4 to RF substrates, PTFE, polyimide, ceramics and glass, to graphene and ITO-coated glass.

In addition, LPKF presents the Contac S4 and MultiPress S4 for manufacturing multilayers with up to eight layers including galvanic through-hole plating – fast and precise for prototype production in-house.

Laser micromachining as contract manufacturing

Under the LaserMicronics brand, LPKF presents its range of services as a contract manufacturer for precise laser micromachining – from small to large series. Partners benefit from non-contact laser cutting for printed circuit boards as well as precision cutting of micro parts made of stainless steel, nickel, molybdenum, or titanium.

Laser plastic welding: Ideal solutions for electronic housings

LPKF offers laser plastic welding solutions for electronic housings and components for use in demanding or sensitive environments. Two new technologies are particularly in focus:

- ATA technology (Absorbing-To-Absorbing) enables the development and series production of new material combinations thanks to the welding of two absorbing components.

- TherMoPro was developed as a thermographic analysis unit for non-destructive quality control in laser welding. In combination with specially developed software, the system ensures optimized quality assurance – whether as a stand-alone or inline installation.

Goes beyond Advanced Packaging: LIDE® technology

LPKF presents its LIDE® technology (Laser Induced Deep Etching) for micromachining thin glass substrates. These systems enable high-precision structuring of glass specifically for demanding applications in the semiconductor industry, such as through-hole plating, displays, or sensors that will be needed in large quantities in the future. LPKF's LIDE® systems are available both as R&D systems and as high-volume systems.

Our experts on site are available to answer your questions. You can find us here:

LPKF Laser & Electronics SE
Hall B2, Booth 305
November 18–21, 2025
Messe München

Those interested can schedule a personal consultation appointment at the trade fair in advance at: https://www.lpkf.com/en/company/trade-shows-events-teaser/productronica-2025

The new LPKF CuttingMaster 2246 for precise laser depaneling will be presented for the first time at productronica 2025

ABOUT LPKF

As a high-tech engineering company, LPKF develops high-precision, scalable manufacturing processes that are used in growth markets such as semiconductors & electronics, life science & medical technology, smart mobility, and research & development. Founded in 1976, the company is headquartered in Garbsen near Hanover and operates worldwide through subsidiaries and agencies. LPKF employs around 700 people and strives tirelessly to drive technological progress with innovative solutions and bring about sustainable, positive changes in the world. The shares of LPKF Laser & Electronics SE are traded on the SDAX of the German Stock Exchange (ISIN 0006450000).

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